



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 5067**
Mizuki NAGAI et al. : **Attorney Docket No. 2003_1338**
Serial No. 10/664,078 : **Group Art Unit 1753**
Filed September 17, 2003 : **Examiner Edna Wong**

COPPER-PLATING LIQUID, PLATING
METHOD AND PLATING APPARATUS

Mail Stop: AF

RESPONSE TO FINAL REJECTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Final Rejection dated August 16, 2005, the period for response having been extended for one month by the attached petition, please amend the present application as follows:

Ok to enter. ON 12/27/05